

**MOULD IN LEATHER...**  
**21 January 2009 - Half Day**  
**Hong Kong**

To: Ms Chi-On Kwok

Email: [conference@aplf.com](mailto:conference@aplf.com)

Tel: (852) 2516 2167

Fax: (852) 3749 7346

**Fax Reply Slip**

Yes, we would like to confirm the attendance at the seminar - "Mould in Leather...".

Conference Fee: US\$250 (for non-exhibitors of APLF or non-member of BLC)

Conference Fee: US\$225 (for exhibitors of APLF or members of BLC only)

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**Mailing Address:**

Please mail to: Ms Chi-on Kwok  
17/F, China Resources Building  
26 Harbour Road  
Wanchai, Hong Kong

Organised by BLC Leather Technology Centre Ltd. and APLF Ltd. For further details, please contact Mr Barry Wood or Ms Chi-on Kwok at [conference@aplf.com](mailto:conference@aplf.com).

